



Material Content Data Sheet



Sales Product Name		BGB 707L7ESD E6327		Issued		20. July 2018		
MA#		MA001159854						
Package		PG-TSLP-7-1		Weight*		1.58 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.002	0.11		1092	
	noble metal	gold	7440-57-5	0.007	0.42		4234	
	inorganic material	silicon	7440-21-3	0.049	3.14	3.67	31378	36704
leadframe	non noble metal	nickel	7440-02-0	0.329	20.87	20.87	208692	208692
wire	noble metal	gold	7440-57-5	0.046	2.90	2.90	29028	29028
encapsulation	inorganic material	antimonytrioxide	1309-64-4	0.001	0.03		343	
	organic material	carbon black	1333-86-4	0.011	0.69		6854	
	plastics	epoxy resin	-	0.146	9.25		92527	
	inorganic material	silicondioxide	60676-86-0	0.923	58.57	68.54	585659	685383
leadfinish	noble metal	gold	7440-57-5	0.032	2.01	2.01	20081	20081
plating	noble metal	gold	7440-57-5	0.032	2.01	2.01	20112	20112
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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